



**THE DATASHEET OF
ADG1414BCPZ-REEL7**



FEATURES

SPI interface

Supports daisy-chain mode

9.5 Ω on resistance at 25°C and ± 15 V dual supply

1.6 Ω on-resistance flatness at 25°C and ± 15 V dual supply

Fully specified at ± 15 V, +12 V, ± 5 V

3 V logic-compatible inputs

Rail-to-rail operation

24-lead TSSOP and 24-lead, 4 mm \times 4 mm LFCSP

APPLICATIONS

Automatic test equipment

Data acquisition systems

Battery-powered systems

Sample-and-hold systems

Audio signal routing

Video signal routing

Communication systems

GENERAL DESCRIPTION

The **ADG1414** is a monolithic complementary metal-oxide semiconductor (CMOS) device containing eight independently selectable switches designed on an industrial CMOS (*i*CMOS[®]) process. *i*CMOS is a modular manufacturing process combining high voltage CMOS and bipolar technologies. *i*CMOS components can tolerate high supply voltages while providing increased performance, dramatically lower power consumption, and reduce the package size.

The **ADG1414** is a set of octal, single-pole, single-throw (SPST) switches controlled via a 3-wire serial interface. On resistance is matched closely between switches and is very flat over the full signal range. Each switch conducts equally well in both directions and the input signal range extends to the supplies.

Data is written to these devices in the form of eight bits; each bit corresponds to one channel.

FUNCTIONAL BLOCK DIAGRAM

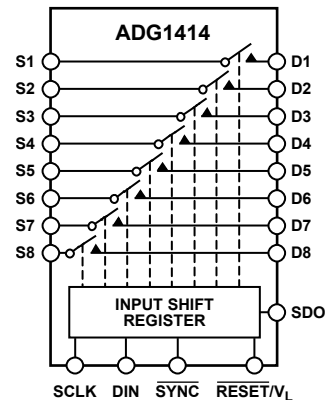


Figure 1.

The **ADG1414** uses a versatile 3-wire serial interface that operates at clock rates of up to 50 MHz and is compatible with standard SPI, QSPI[™], MICROWIRE[™], and DSP interface standards. The output of the shift register, SDO, enables a number of these devices to be daisy chained.

At power-up, all switches are in the off condition, and the internal registers contain all zeros.

PRODUCT HIGHLIGHTS

1. 50 MHz serial interface.
2. 9.5 Ω on resistance.
3. 1.6 Ω on-resistance flatness.
4. 24-lead TSSOP and 4 mm \times 4 mm LFCSP packages.

Rev. B

Document Feedback

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REVISION HISTORY

11/15—Rev. A to Rev. B

| | |
|---|----|
| Changes to V_{DD}/V_{SS} Parameter, Table 2 | 5 |
| Updated Outline Dimensions | 19 |

1/13—Rev. 0 to Rev. A

| | |
|--|----|
| Changes to $\overline{\text{RESET}}/V_L$ Pin Description Column, Table 9 | 11 |
| Changes to Power-On Reset Section..... | 19 |
| Updated Outline Dimensions | 20 |

10/09—Revision 0: Initial Version

SPECIFICATIONS

±15 V DUAL SUPPLY

$V_{DD} = 15\text{ V} \pm 10\%$, $V_{SS} = -15\text{ V} \pm 10\%$, $V_L = 2.7\text{ V}$ to 5.5 V , $GND = 0\text{ V}$, unless otherwise noted.

Table 1.

| Parameter | +25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|--|-------------|-------------------|----------------------|-------------------|--|
| ANALOG SWITCH | | | | | |
| Analog Signal Range | | | V_{SS} to V_{DD} | V | |
| On Resistance (R_{ON}) | 9.5 | | | Ω typ | $V_{DD} = +13.5\text{ V}$, $V_{SS} = -13.5\text{ V}$, $V_S = \pm 10\text{ V}$, $I_S = -10\text{ mA}$; see Figure 23 |
| On-Resistance Match Between Channels (ΔR_{ON}) | 11.5 | 14 | 16 | Ω max | |
| | 0.55 | | | Ω typ | $V_{DD} = +13.5\text{ V}$, $V_{SS} = -13.5\text{ V}$, $V_S = \pm 10\text{ V}$, $I_S = -10\text{ mA}$ |
| On-Resistance Flatness ($R_{FLAT(ON)}$) | 1 | 1.5 | 1.7 | Ω max | |
| | 1.6 | | | Ω typ | $V_{DD} = +13.5\text{ V}$, $V_{SS} = -13.5\text{ V}$, $V_S = \pm 10\text{ V}$, $I_S = -10\text{ mA}$ |
| | 1.9 | 2.15 | 2.3 | Ω max | |
| LEAKAGE CURRENTS | | | | | |
| Source Off Leakage, I_S (Off) | ± 0.05 | | | nA typ | $V_{DD} = +16.5\text{ V}$, $V_{SS} = -16.5\text{ V}$ $V_S = \pm 10\text{ V}$, $V_D = \mp 10\text{ V}$; see Figure 24 |
| | ± 0.15 | ± 1 | ± 2 | nA max | |
| Drain Off Leakage, I_D (Off) | ± 0.05 | | | nA typ | $V_S = \pm 10\text{ V}$, $V_D = \mp 10\text{ V}$; see Figure 24 |
| | ± 0.15 | ± 1 | ± 2 | nA max | |
| Channel On Leakage, I_D , I_S (On) | ± 0.1 | | | nA typ | $V_S = V_D = \pm 10\text{ V}$; see Figure 25 |
| | ± 0.3 | ± 2 | ± 4 | nA max | |
| DIGITAL INPUTS | | | | | |
| Input High Voltage (V_{INH}) | | | 2.0 | V min | |
| Input Low Voltage (V_{INL}) | | | 0.8 | V max | |
| Input Current | ± 0.001 | | | μA typ | $V_{IN} = V_{GND}$ or V_L |
| | | | ± 0.1 | μA max | |
| Digital Input Capacitance (C_{IN}) | 4 | | | pF typ | |
| LOGIC OUTPUTS (SDO) | | | | | |
| Output Low Voltage (V_{OL}) ¹ | | | 0.4 | V max | $I_{SINK} = 3\text{ mA}$ |
| | | | 0.6 | V max | $I_{SINK} = 6\text{ mA}$ |
| High Impedance Leakage Current | 0.001 | | | μA typ | |
| | | | ± 1 | μA max | |
| High Impedance Output Capacitance ¹ | 4 | | | pF typ | |
| DYNAMIC CHARACTERISTICS ¹ | | | | | |
| t_{ON} | 75 | | | ns typ | $R_L = 100\ \Omega$, $C_L = 35\text{ pF}$ |
| | 93 | 110 | 120 | ns max | $V_S = 10\text{ V}$; see Figure 30 |
| t_{OFF} | 25 | | | ns typ | $R_L = 100\ \Omega$, $C_L = 35\text{ pF}$ |
| | 35 | 35 | 35 | ns max | $V_S = 10\text{ V}$; see Figure 30 |
| Charge Injection | 10 | | | pC typ | $V_S = 0\text{ V}$, $R_S = 0\ \Omega$, $C_L = 1\text{ nF}$; see Figure 31 |
| Off Isolation | -73 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 26 |
| Channel-to-Channel Crosstalk | -75 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 27 |
| Total Harmonic Distortion (THD + N) | 0.05 | | | % typ | $R_L = 110\ \Omega$, 15 V p-p , $f = 20\text{ Hz}$ to 20 kHz ; see Figure 29 |
| -3 dB Bandwidth | 256 | | | MHz typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$; see Figure 28 |
| Insertion Loss | 0.55 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 28 |
| C_D , C_S (Off) | 8 | | | pF typ | $f = 1\text{ MHz}$ |
| C_D , C_S (On) | 32 | | | pF typ | $f = 1\text{ MHz}$ |

| Parameter | +25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|---------------------------|-------|----------------|-------------------------|--|--|
| POWER REQUIREMENTS | | | | | |
| I_{DD} | 0.001 | | 1 | μA typ μA max | $V_{DD} = +16.5\text{ V}$, $V_{SS} = -16.5\text{ V}$ Digital inputs = 0 V or V_L |
| I_L Inactive | 0.3 | | 1 | μA typ μA max | Digital inputs = 0 V or V_L |
| I_L Active at 30 MHz | 0.26 | | 1 | mA typ mA max | Digital inputs toggle between 0 V and V_L |
| I_L Active at 50 MHz | 0.42 | 0.3 | 0.35 | mA typ mA max | Digital inputs toggle between 0 V and V_L |
| I_{SS} | 0.001 | 0.5 | 0.55 | mA typ mA max | Digital inputs = 0 V or V_L |
| V_{DD}/V_{SS} | | | 1 $\pm 4.5/\pm 16.5$ | μA max V min/max | |

¹ Guaranteed by design, not subject to production test.

12 V SINGLE SUPPLY

$V_{DD} = 12\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$, $V_L = 2.7\text{ V}$ to 5.5 V, GND = 0 V, unless otherwise noted.

Table 2.

| Parameter | +25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|--|-------------|----------------|-----------------|--|--|
| ANALOG SWITCH | | | | | |
| Analog Signal Range | | | 0 to V_{DD} | V | |
| On Resistance (R_{ON}) | 18 | | | Ω typ | $V_{DD} = 10.8\text{ V}$, $V_{SS} = 0\text{ V}$; $V_S = 0\text{ V}$ to 10 V, $I_S = -10\text{ mA}$; see Figure 23 |
| On-Resistance Match Between Channels (ΔR_{ON}) | 21.5 | 26 | 28.5 | Ω max Ω typ | $V_{DD} = 10.8\text{ V}$, $V_{SS} = 0\text{ V}$; $V_S = 0\text{ V}$ to 10 V, $I_S = -10\text{ mA}$ |
| On-Resistance Flatness ($R_{FLAT(ON)}$) | 1.2 | 1.6 | 1.8 | Ω max Ω typ | $V_{DD} = 10.8\text{ V}$, $V_{SS} = 0\text{ V}$; $V_S = 0\text{ V}$ to 10 V, $I_S = -10\text{ mA}$ |
| | 6 | 6.9 | 7.3 | Ω max | |
| LEAKAGE CURRENTS | | | | | |
| Source Off Leakage, I_S (Off) | ± 0.02 | | | nA typ nA max | $V_{DD} = 10.8\text{ V}$ $V_S = 1\text{ V}/10\text{ V}$, $V_D = 10\text{ V}/1\text{ V}$; see Figure 24 |
| Drain Off Leakage, I_D (Off) | ± 0.15 | ± 1 | ± 2 | nA typ nA max | $V_S = 1\text{ V}/10\text{ V}$, $V_D = 10\text{ V}/1\text{ V}$; see Figure 24 |
| Channel On Leakage, I_D , I_S (On) | ± 0.02 | ± 1 | ± 2 | nA typ nA max | $V_S = V_D = 1\text{ V}$ or 10 V; see Figure 25 |
| | ± 0.05 | ± 2 | ± 4 | nA typ nA max | |
| DIGITAL INPUTS | | | | | |
| Input High Voltage (V_{INH}) | | | 2.0 | V min | |
| Input Low Voltage (V_{INL}) | | | 0.8 | V max | |
| Input Current | ± 0.001 | | | μA typ μA max | $V_{IN} = V_{GND}$ or V_L |
| Digital Input Capacitance (C_{IN}) | 4 | | | pF typ | |
| LOGIC OUTPUTS (SDO) | | | | | |
| Output Low Voltage (V_{OL}) ¹ | | | 0.4 | V max | $I_{SINK} = 3\text{ mA}$ |
| | | | 0.6 | V max | $I_{SINK} = 6\text{ mA}$ |
| High Impedance Leakage Current | | | ± 1 | μA max | |
| High Impedance Output Capacitance ¹ | 4 | | | pF typ | |

| Parameter | +25°C | -40°C to | | Unit | Test Conditions/Comments |
|--|-------|----------|--------|-----------|--|
| | | +85°C | +125°C | | |
| DYNAMIC CHARACTERISTICS¹ | | | | | |
| t _{ON} | 145 | | | ns typ | R _L = 100 Ω, C _L = 35 pF |
| | 185 | 220 | 240 | ns max | V _S = 8 V; see Figure 30 |
| t _{OFF} | 35 | | | ns typ | R _L = 100 Ω, C _L = 35 pF |
| | 45 | 46 | 46 | ns max | V _S = 8 V; see Figure 30 |
| Charge Injection | 8 | | | pC typ | V _S = 6 V, R _S = 0 Ω, C _L = 1 nF; see Figure 31 |
| Off Isolation | -70 | | | dB typ | R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 26 |
| Channel-to-Channel Crosstalk | -75 | | | dB typ | R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 27 |
| -3 dB Bandwidth | 240 | | | MHz typ | R _L = 50 Ω, C _L = 5 pF; see Figure 28 |
| Insertion Loss | 1.15 | | | dB typ | R _L = 50 Ω, C _L = 5 pF, f = 1 MHz; see Figure 28 |
| C _D , C _S (Off) | 12 | | | pF typ | f = 1 MHz |
| C _D , C _S (On) | 33 | | | pF typ | f = 1 MHz |
| POWER REQUIREMENTS | | | | | |
| I _{DD} | 0.001 | | | μA typ | V _{DD} = +13.2 V |
| | | | 1 | μA max | Digital inputs = 0 V or V _L |
| I _L Inactive | 0.3 | | | μA typ | Digital inputs = 0 V or V _L |
| | | | 1 | μA max | |
| I _L Active at 30 MHz | 0.26 | | | mA typ | Digital inputs toggle between 0 V and V _L |
| | | 0.3 | 0.35 | mA max | |
| I _L Active at 50 MHz | 0.42 | | | mA typ | Digital inputs toggle between 0 V and V _L |
| | | 0.5 | 0.55 | mA max | |
| I _{SS} | 0.001 | | | μA typ | Digital inputs = 0 V or V _L |
| | | | 1 | μA max | |
| V _{DD} /V _{SS} | | | 5/16.5 | V min/max | |

¹ Guaranteed by design, not subject to production test.

±5 V DUAL SUPPLY

$V_{DD} = +5\text{ V} \pm 10\%$, $V_{SS} = -5\text{ V} \pm 10\%$, $V_L = 2.7\text{ V}$ to V_{DD} , $GND = 0\text{ V}$, unless otherwise noted.

Table 3.

| Parameter | +25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|--|-------------|-------------------|----------------------|-------------------|--|
| ANALOG SWITCH | | | | | |
| Analog Signal Range | | | V_{SS} to V_{DD} | V | |
| On Resistance (R_{ON}) | 21 | | | Ω typ | $V_{DD} = +4.5\text{ V}$, $V_{SS} = -4.5\text{ V}$, $V_S = \pm 4.5\text{ V}$, $I_S = -10\text{ mA}$; see Figure 23 |
| | | 29 | 32 | Ω max | |
| On-Resistance Match Between Channels (ΔR_{ON}) | 0.6 | | | Ω typ | $V_{DD} = +4.5\text{ V}$, $V_{SS} = -4.5\text{ V}$, $V_S = \pm 4.5\text{ V}$, $I_S = -10\text{ mA}$ |
| | | 1.7 | 1.9 | Ω max | |
| On-Resistance Flatness ($R_{FLAT(ON)}$) | 1.3 | | | Ω typ | $V_{DD} = +4.5\text{ V}$, $V_{SS} = -4.5\text{ V}$, $V_S = \pm 4.5\text{ V}$; $I_S = -10\text{ mA}$ |
| | 6.4 | 7.3 | 7.6 | Ω max | |
| LEAKAGE CURRENTS | | | | | |
| Source Off Leakage, I_S (Off) | ± 0.02 | | | nA typ | $V_{DD} = +5.5\text{ V}$, $V_{SS} = -5.5\text{ V}$ $V_S = \pm 4.5\text{ V}$, $V_D = \mp 4.5\text{ V}$; see Figure 24 |
| | ± 0.15 | ± 1 | ± 2 | nA max | |
| Drain Off Leakage, I_D (Off) | ± 0.02 | | | nA typ | $V_S = \pm 4.5\text{ V}$, $V_D = \mp 4.5\text{ V}$; see Figure 24 |
| | ± 0.15 | ± 1 | ± 2 | nA max | |
| Channel On Leakage, I_D , I_S (On) | ± 0.05 | | | nA typ | $V_S = V_D = \pm 4.5\text{ V}$; see Figure 25 |
| | ± 0.3 | ± 2 | ± 4 | nA max | |
| DIGITAL INPUTS | | | | | |
| Input High Voltage (V_{INH}) | | | 2.0 | V min | |
| Input Low Voltage (V_{INL}) | | | 0.8 | V max | |
| Input Current | ± 0.001 | | | μA typ | $V_{IN} = V_{GND}$ or V_L |
| | | | ± 0.1 | μA max | |
| Digital Input Capacitance (C_{IN}) | 4 | | | pF typ | |
| LOGIC OUTPUTS (SDO) | | | | | |
| Output Low Voltage (V_{OL}) ¹ | | | 0.4 | V max | $I_{SINK} = 3\text{ mA}$ |
| | | | 0.6 | V max | $I_{SINK} = 6\text{ mA}$ |
| High Impedance Leakage Current | | | ± 1 | μA max | |
| High Impedance Output Capacitance ¹ | 4 | | | pF typ | |
| DYNAMIC CHARACTERISTICS¹ | | | | | |
| t_{ON} | 190 | | | ns typ | $R_L = 100\ \Omega$, $C_L = 35\text{ pF}$ |
| | 250 | 290 | 320 | ns max | $V_S = 3\text{ V}$; see Figure 30 |
| t_{OFF} | 45 | | | ns typ | $R_L = 100\ \Omega$, $C_L = 35\text{ pF}$ |
| | 60 | 65 | 70 | ns max | $V_S = 3\text{ V}$; see Figure 30 |
| Charge Injection | 7 | | | pC typ | $V_S = 0\text{ V}$, $R_S = 0\ \Omega$, $C_L = 1\text{ nF}$; see Figure 31 |
| Off Isolation | -70 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 26 |
| Channel-to-Channel Crosstalk | -75 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 27 |
| Total Harmonic Distortion (THD + N) | 0.14 | | | % typ | $R_L = 110\ \Omega$, 5 V p-p, $f = 20\text{ Hz}$ to 20 kHz; see Figure 29 |
| -3 dB Bandwidth | 256 | | | MHz typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$; see Figure 28 |
| Insertion Loss | 1 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 28 |
| C_D , C_S (Off) | 11 | | | pF typ | $f = 1\text{ MHz}$ |
| C_D , C_S (On) | 35 | | | pF typ | $f = 1\text{ MHz}$ |

| Parameter | +25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|---------------------------|-------|----------------|--------------------|--|--|
| POWER REQUIREMENTS | | | | | |
| I_{DD} | 0.001 | | 1 | $\mu\text{A typ}$ $\mu\text{A max}$ | $V_{DD} = +5.5\text{ V}$, $V_{SS} = -5.5\text{ V}$ Digital inputs = 0 V or V_L |
| I_L Inactive | 0.3 | | 1 | $\mu\text{A typ}$ $\mu\text{A max}$ | Digital inputs = 0 V or V_L |
| I_L Active at 30 MHz | 0.26 | | 1 | mA typ mA max | Digital inputs toggle between 0 V and V_L |
| I_L Active at 50 MHz | 0.42 | 0.3 | 0.35 | mA typ mA max | Digital inputs toggle between 0 V and V_L |
| I_{SS} | 0.001 | 0.5 | 0.55 | $\mu\text{A typ}$ $\mu\text{A max}$ | Digital inputs = 0 V or V_L |
| V_{DD}/V_{SS} | | | 1 | $\mu\text{A max}$ | |
| | | | $\pm 4.5/\pm 16.5$ | V min/max | |

¹ Guaranteed by design, not subject to production test.

CONTINUOUS CURRENT PER CHANNEL

Guaranteed by design, not subject to production test.

Table 4. Eight Channels On

| Parameter | 25°C | 85°C | 125°C | Unit | Test Conditions/Comments |
|---|------|------|-------|-----------------|---|
| CONTINUOUS CURRENT PER CHANNEL | | | | | |
| $\pm 15\text{ V Dual Supply}$ | | | | | $V_{DD} = +13.5\text{ V}$, $V_{SS} = -13.5\text{ V}$ |
| 24-Lead TSSOP ($\theta_{JA} = 112.6^\circ\text{C/W}$) | 67 | 46 | 31 | mA max | |
| 24-Lead LFCSP ($\theta_{JA} = 30.4^\circ\text{C/W}$) | 121 | 75 | 42 | mA max | |
| $12\text{ V Single Supply}$ | | | | | $V_{DD} = 10.8\text{ V}$, $V_{SS} = 0\text{ V}$ |
| 24-Lead TSSOP ($\theta_{JA} = 112.6^\circ\text{C/W}$) | 64 | 44 | 30 | mA max | |
| 24-Lead LFCSP ($\theta_{JA} = 30.4^\circ\text{C/W}$) | 115 | 72 | 41 | mA max | |
| $\pm 5\text{ V Dual Supply}$ | | | | | $V_{DD} = +4.5\text{ V}$, $V_{SS} = -4.5\text{ V}$ |
| 24-Lead TSSOP ($\theta_{JA} = 112.6^\circ\text{C/W}$) | 48 | 35 | 22 | mA max | |
| 24-Lead LFCSP ($\theta_{JA} = 30.4^\circ\text{C/W}$) | 86 | 57 | 36 | mA max | |

Guaranteed by design and characterization, not production tested.

Table 5. One Channel On

| Parameter | 25°C | 85°C | 125°C | Unit | Test Conditions/Comments |
|---|------|------|-------|-----------------|---|
| CONTINUOUS CURRENT PER CHANNEL | | | | | |
| $\pm 15\text{ V Dual Supply}$ | | | | | $V_{DD} = +13.5\text{ V}$, $V_{SS} = -13.5\text{ V}$ |
| 24-Lead TSSOP ($\theta_{JA} = 112.6^\circ\text{C/W}$) | 169 | 97 | 48 | mA max | |
| 24-Lead LFCSP ($\theta_{JA} = 30.4^\circ\text{C/W}$) | 295 | 139 | 55 | mA max | |
| $12\text{ V Single Supply}$ | | | | | $V_{DD} = 10.8\text{ V}$, $V_{SS} = 0\text{ V}$ |
| 24-Lead TSSOP ($\theta_{JA} = 112.6^\circ\text{C/W}$) | 161 | 93 | 47 | mA max | |
| 24-Lead LFCSP ($\theta_{JA} = 30.4^\circ\text{C/W}$) | 281 | 135 | 54 | mA max | |
| $\pm 5\text{ V Dual Supply}$ | | | | | $V_{DD} = +4.5\text{ V}$, $V_{SS} = -4.5\text{ V}$ |
| 24-Lead TSSOP ($\theta_{JA} = 112.6^\circ\text{C/W}$) | 122 | 76 | 43 | mA max | |
| 24-Lead LFCSP ($\theta_{JA} = 30.4^\circ\text{C/W}$) | 214 | 114 | 51 | mA max | |

TIMING CHARACTERISTICS

All input signals are specified with $t_{R} = t_{F} = 1 \text{ ns/V}$ (10% to 90% of V_{DD}) and timed from a voltage level of $(V_{IL} + V_{IH})/2$ (see Figure 2). $V_{DD} = 4.5 \text{ V}$ to 16.5 V ; $V_{SS} = -16.5 \text{ V}$ to 0 V ; $V_L = 2.7 \text{ V}$ to 5.5 V or V_{DD} (whichever is less); $GND = 0 \text{ V}$; all specifications T_{MIN} to T_{MAX} , unless otherwise noted. Guaranteed by design and characterization, not production tested.

Table 6.

| Parameter | Limit at T_{MIN}, T_{MAX} | Unit | Conditions/Comments |
|------------|-----------------------------|--------|---|
| t_1^1 | 20 | ns min | SCLK cycle time |
| t_2 | 9 | ns min | SCLK high time |
| t_3 | 9 | ns min | SCLK low time |
| t_4 | 5 | ns min | SYNC to SCLK active edge setup time |
| t_5 | 5 | ns min | Data setup time |
| t_6 | 5 | ns min | Data hold time |
| t_7 | 5 | ns min | SCLK active edge to SYNC rising edge |
| t_8 | 15 | ns min | Minimum SYNC high time |
| t_9 | 5 | ns min | SYNC rising edge to next SCLK active edge ignored |
| t_{10} | 5 | ns min | SCLK active edge to SYNC falling edge ignored |
| t_{11}^2 | 40 | ns max | SCLK rising edge to SDO valid |
| t_{12} | 15 | ns min | Minimum RESET pulse width |

¹ Maximum SCLK frequency is 50 MHz at $V_{DD} = 4.5 \text{ V}$ to 16.5 V ; $V_{SS} = -16.5 \text{ V}$ to 0 V , $V_L = 2.7 \text{ V}$ to 5.5 V or V_{DD} (whichever is less); $GND = 0 \text{ V}$.

² Measured with the 1 kΩ pull-up resistor to V_L and 20 pF load. t_{11} determines the maximum SCLK frequency in daisy-chain mode.

Timing Diagrams

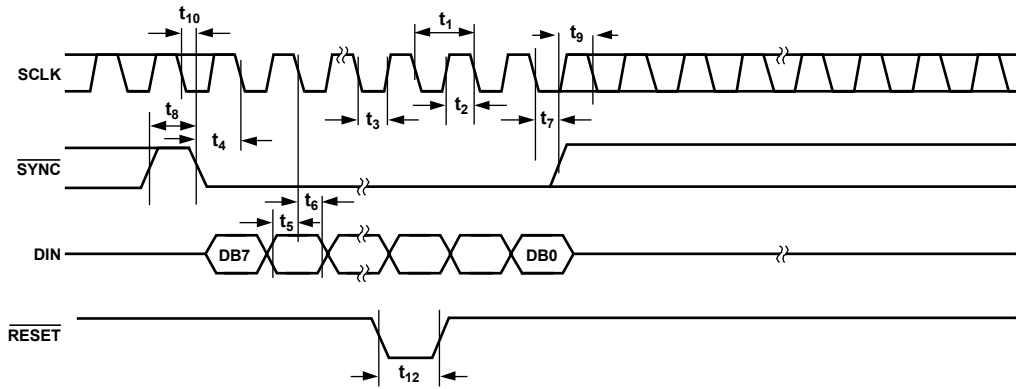


Figure 2. Serial Write Operation

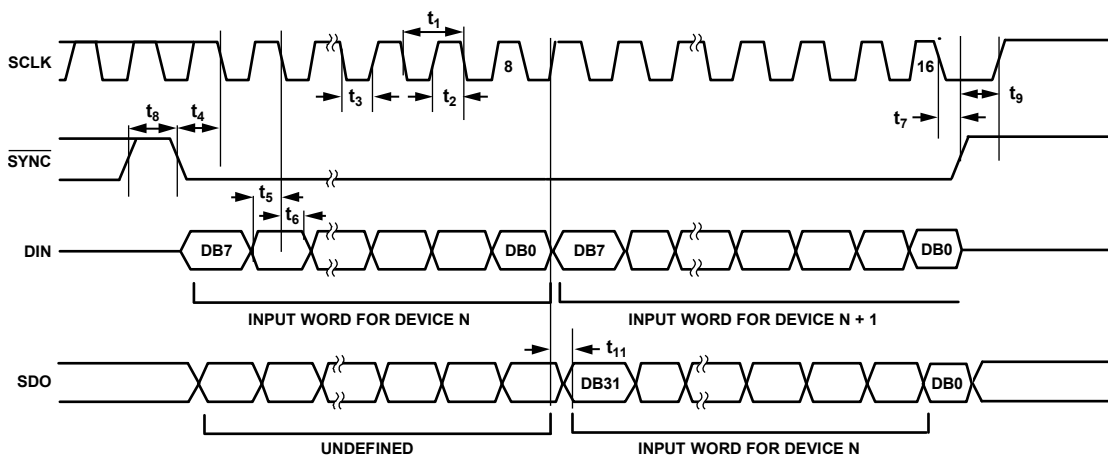


Figure 3. Daisy-Chain Timing Diagram

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 7.

| Parameter | Rating |
|--|--|
| V_{DD} to V_{SS} | 35 V |
| V_{DD} to GND | -0.3 V to +25 V |
| V_{SS} to GND | +0.3 V to -25 V |
| V_L to GND | -0.3 V to +7 V |
| Analog Inputs ¹ | $V_{SS} - 0.3\text{ V}$ to $V_{DD} + 0.3\text{ V}$ or 30 mA, whichever occurs first |
| Digital Inputs ¹ | GND - 0.3 V to $V_L + 0.3\text{ V}$ or 30 mA, whichever occurs first |
| Continuous Current, Sx or Dx Pins | Table 4 specifications + 15% |
| Peak Current, Sx or Dx (Pulsed at 1 ms, 10% Duty Cycle Maximum) | |
| TSSOP Package | 300 mA |
| LFCSP Package | 400 mA |
| Operating Temperature Range | |
| Industrial (B Version) | -40°C to +125°C |
| Storage Temperature Range | -65°C to +150°C |
| Junction Temperature | 150°C |
| Reflow Soldering Peak Temperature, Pb free | 260°C |
| Time at Peak Temperature | 10 sec to 40 sec |

¹ Overvoltages at the analog and digital inputs are clamped by internal diodes. Limit the current to the maximum ratings given.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

Only one absolute maximum rating may be applied at any one time.

THERMAL RESISTANCE

Table 8. Thermal Resistance

| Package Type | θ_{JA} | θ_{JC} | Unit |
|----------------------------|---------------|---------------|------|
| 24-Lead TSSOP ¹ | 112.6 | 50 | °C/W |
| 24-Lead LFCSP ² | 30.4 | | °C/W |

¹ 4-layer board.

² 4-layer board and exposed paddle soldered to V_{SS} .

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

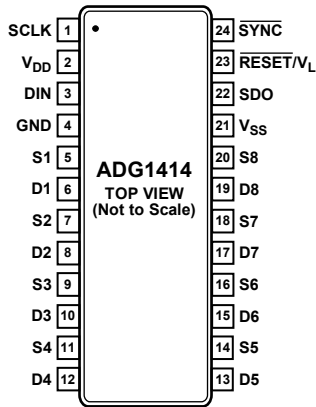


Figure 4. TSSOP Pin Configuration

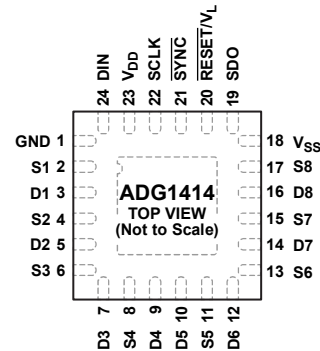


Figure 5. LFCSP Pin Configuration

Table 9. Pin Function Descriptions

| Pin No. | | Mnemonic | Description |
|---------|-------|----------------------|---|
| TSSOP | LFCSP | | |
| 1 | 22 | SCLK | Serial Clock Input. Data is clocked into the input shift register on the falling edge of the serial clock input. Data can be transferred at rates of up to 50 MHz. |
| 2 | 23 | V _{DD} | Most Positive Power Supply Potential. |
| 3 | 24 | DIN | Serial Data Input. This device has an 8-bit shift register. Data is clocked into the register on the falling edge of the serial clock input. |
| 4 | 1 | GND | Ground (0 V) Reference. |
| 5 | 2 | S1 | Source Terminal 1. This pin can be an input or an output. |
| 6 | 3 | D1 | Drain Terminal 1. This pin can be an input or an output. |
| 7 | 4 | S2 | Source Terminal 2. This pin can be an input or an output. |
| 8 | 5 | D2 | Drain Terminal 2. This pin can be an input or an output. |
| 9 | 6 | S3 | Source Terminal 3. This pin can be an input or an output. |
| 10 | 7 | D3 | Drain Terminal 3. This pin can be an input or an output. |
| 11 | 8 | S4 | Source Terminal 4. This pin can be an input or an output. |
| 12 | 9 | D4 | Drain Terminal 4. This pin can be an input or an output. |
| 13 | 10 | D5 | Drain Terminal 5. This pin can be an input or an output. |
| 14 | 11 | S5 | Source Terminal 5. This pin can be an input or an output. |
| 15 | 12 | D6 | Drain Terminal 6. This pin can be an input or an output. |
| 16 | 13 | S6 | Source Terminal 6. This pin can be an input or an output. |
| 17 | 14 | D7 | Drain Terminal 7. This pin can be an input or an output. |
| 18 | 15 | S7 | Source Terminal 7. This pin can be an input or an output. |
| 19 | 16 | D8 | Drain Terminal 8. This pin can be an input or an output. |
| 20 | 17 | S8 | Source Terminal 8. This pin can be an input or an output. |
| 21 | 18 | V _{SS} | Most Negative Power Supply Potential. In single-supply applications, it can be connected to ground. |
| 22 | 19 | SDO | Serial Data Output. This pin can be used for daisy-chaining a number of these devices together or for reading back the data in the shift register for diagnostic purposes. The serial data is transferred on the rising edge of SCLK and is valid on the falling edge of the clock. Pull this open-drain output to the supply with an external resistor. |
| 23 | 20 | RESET/V _L | RESET/Logic Power Supply Input (V _L). Under normal operation, drive the RESET/V _L pin with a 2.7 V to 5 V supply. Pull the pin low (<0.8 V) for a short period of time (15 ns is sufficient) to complete a hardware reset. All switches are opened, and the appropriate registers are cleared to 0. When using the RESET/V _L pin to complete a hardware reset, all other SPI pins (SYNC, SCLK, and DIN) must be driven low. |

| Pin No. | | Mnemonic | Description |
|------------------|-------|--------------------------|--|
| TSSOP | LFCSP | | |
| 24 | 21 | $\overline{\text{SYNC}}$ | Active Low Control Input. This is the frame synchronization signal for the input data. When $\overline{\text{SYNC}}$ goes low, it powers on the SCLK and DIN buffers and enables the input shift register. Data is transferred in on the falling edges of the following clocks. Taking $\overline{\text{SYNC}}$ high updates the switch condition. |
| N/A ¹ | EP | Exposed Pad | Exposed Pad. Exposed pad tied to the substrate, V _{SS} . |

¹ N/A means not applicable.

TYPICAL PERFORMANCE CHARACTERISTICS

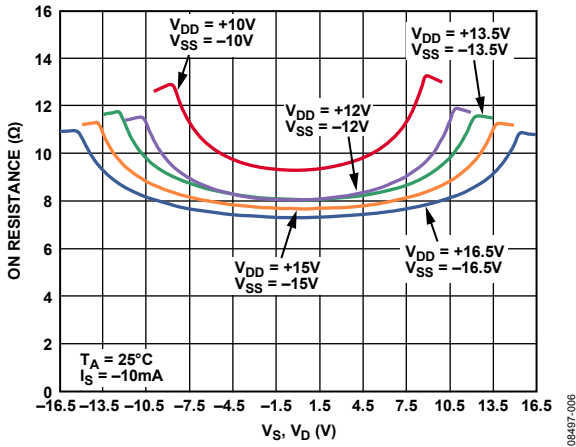


Figure 6. On Resistance as a Function of V_D (V_S), Dual Supply ($V_{DD} = 10\text{ V to }16.5\text{ V}$ and $V_{SS} = -10\text{ V to }-16.5\text{ V}$)

08497-006

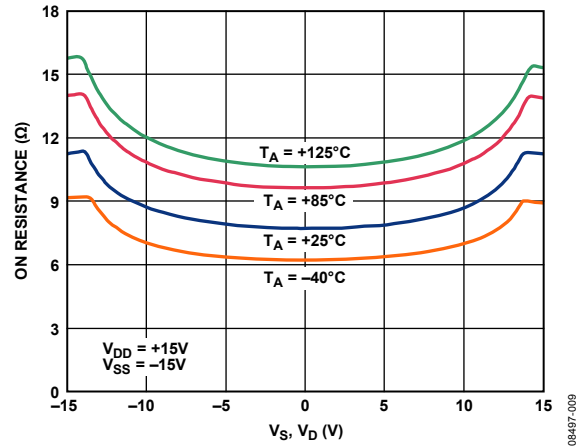


Figure 9. On Resistance as a Function of V_D (V_S), for Different Temperatures, $\pm 15\text{ V Dual Supply}$

08497-008

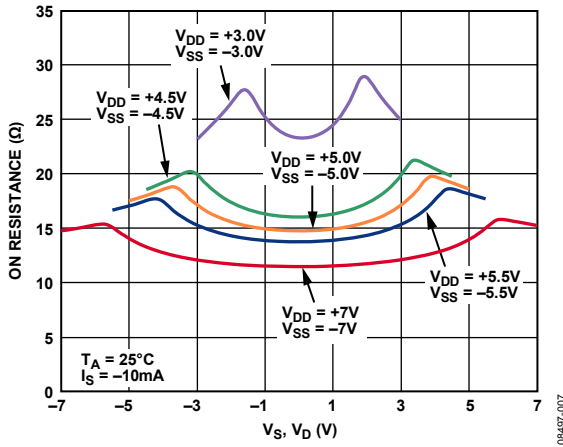


Figure 7. On Resistance as a Function of V_D (V_S), Dual Supply ($V_{DD} = 3.0\text{ V to }7\text{ V}$ and $V_{SS} = -3.0\text{ V to }-7\text{ V}$)

08497-007

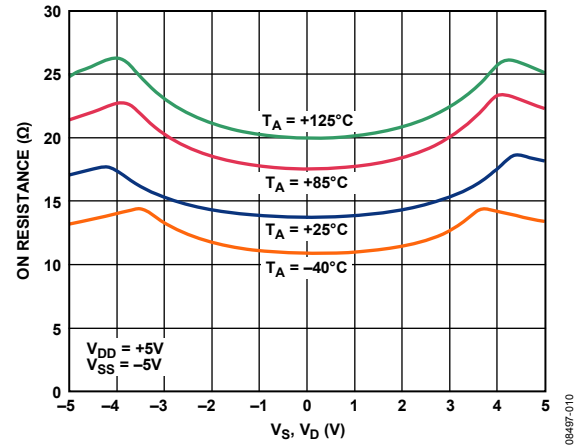


Figure 10. On Resistance as a Function of V_D (V_S), for Different Temperatures, $\pm 5\text{ V Dual Supply}$

08497-010

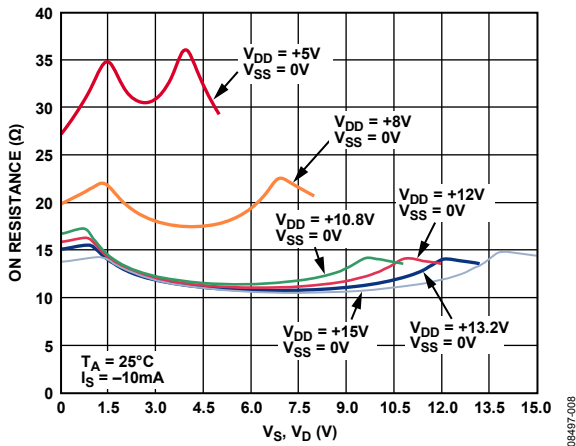


Figure 8. On Resistance as a Function of V_D (V_S), Single Supply

08497-008

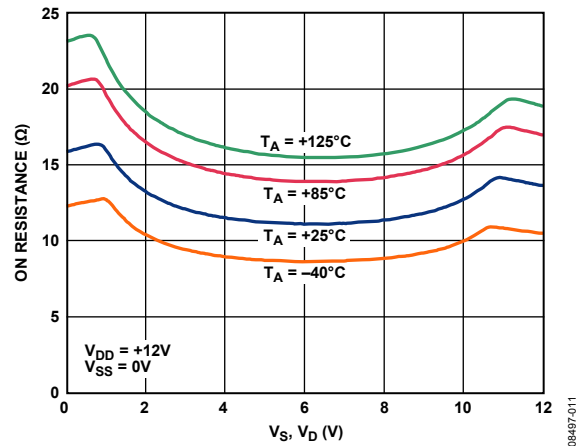


Figure 11. On Resistance as a Function of V_D (V_S), for Different Temperatures, $12\text{ V Single Supply}$

08497-011

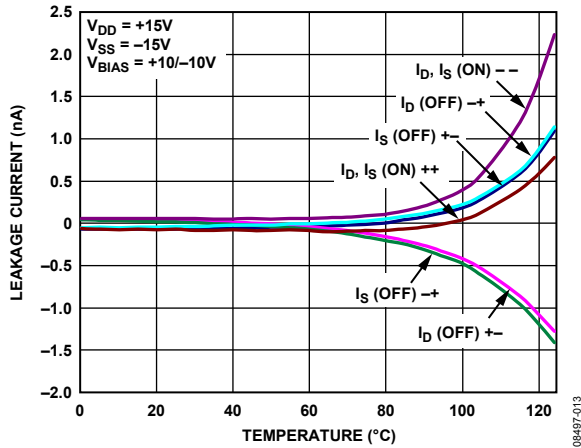


Figure 12. Leakage Current as a Function of Temperature, ±15 V Dual Supply

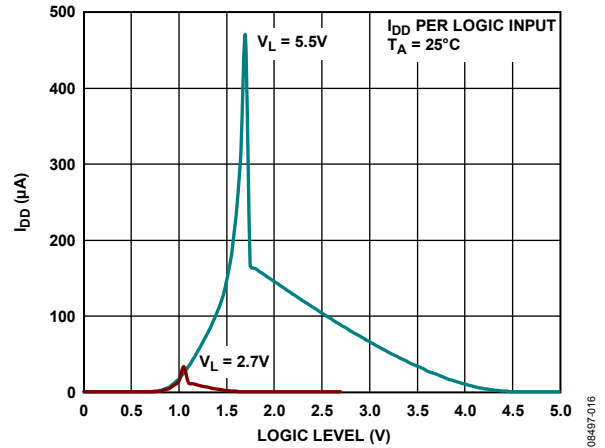


Figure 15. I_{DD} vs. Logic Level

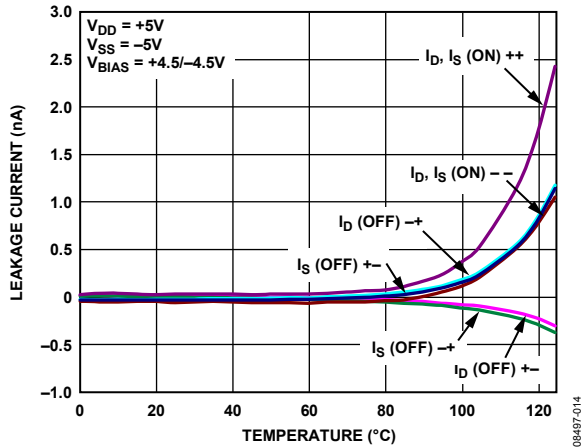


Figure 13. Leakage Current as a Function of Temperature, ±5 V Dual Supply

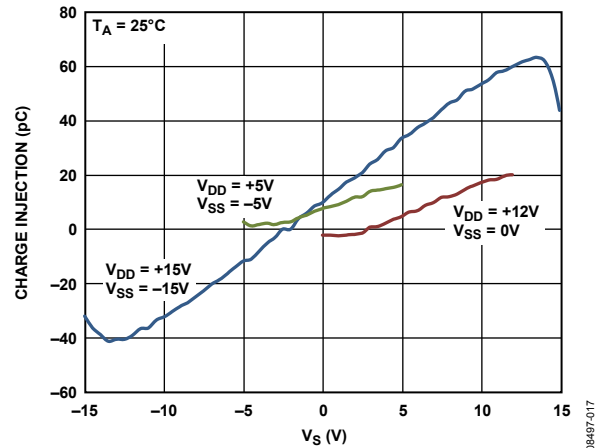


Figure 16. Charge Injection vs. Source Voltage (V_S)

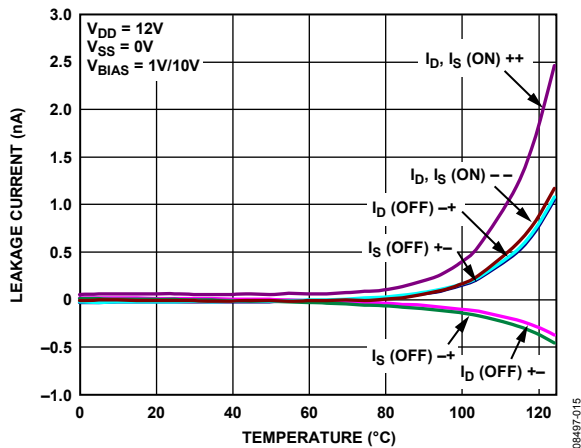


Figure 14. Leakage Current as a Function of Temperature, 12 V Single Supply

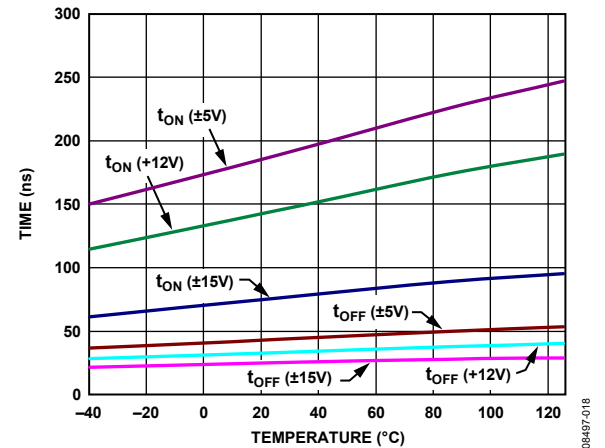


Figure 17. Transition Time vs. Temperature

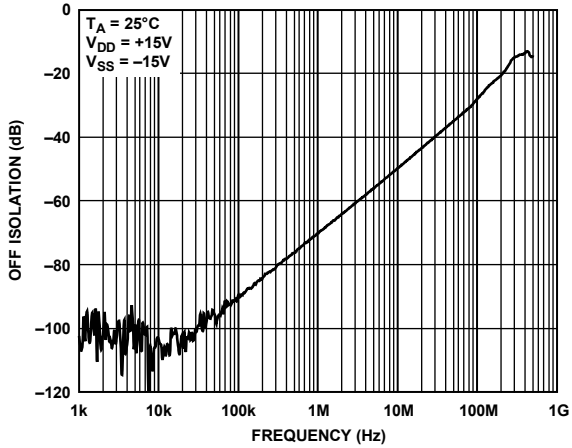


Figure 18. Off Isolation vs. Frequency

08497-019

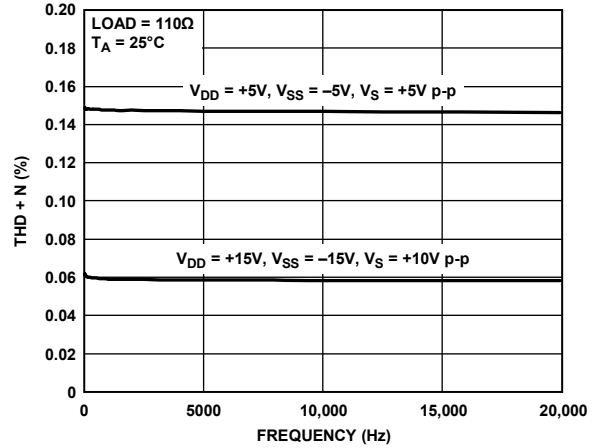


Figure 21. THD + N vs. Frequency, ±15 V Dual Supply

08497-023

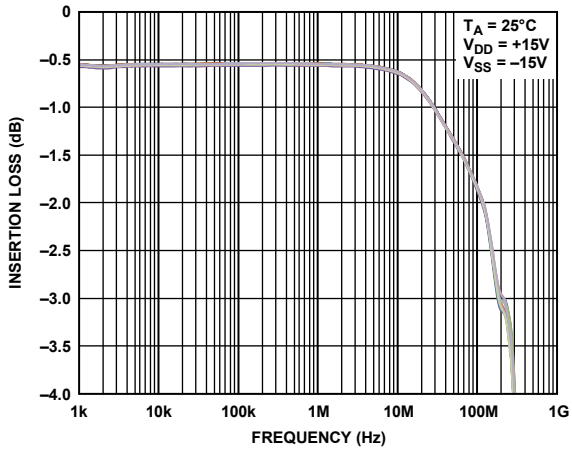


Figure 19. On Response vs. Frequency

08497-012

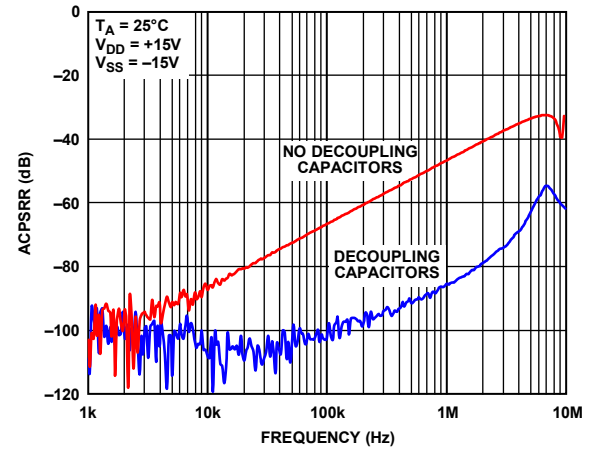


Figure 22. ACPSRR vs. Frequency

08497-025

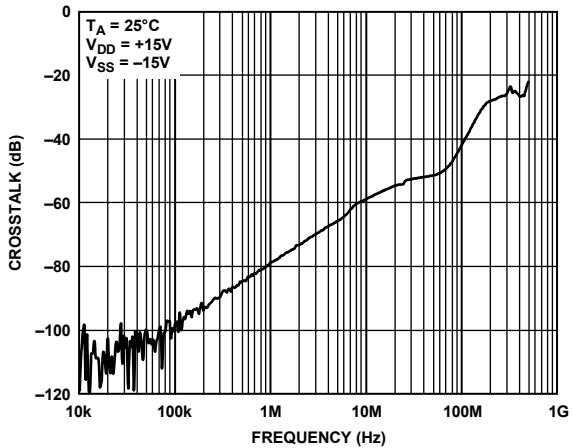


Figure 20. Crosstalk vs. Frequency

08497-021

TEST CIRCUITS

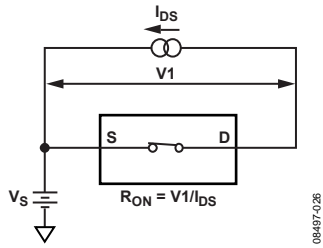


Figure 23. On Resistance

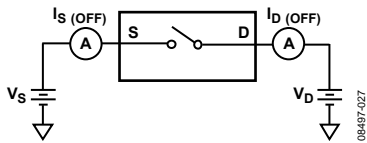


Figure 24. Off Leakage

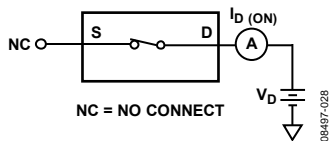


Figure 25. On Leakage

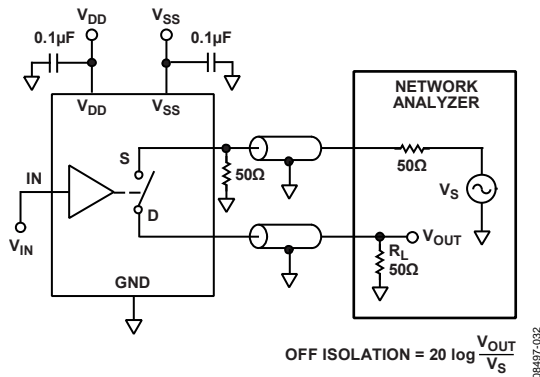


Figure 26. Off Isolation

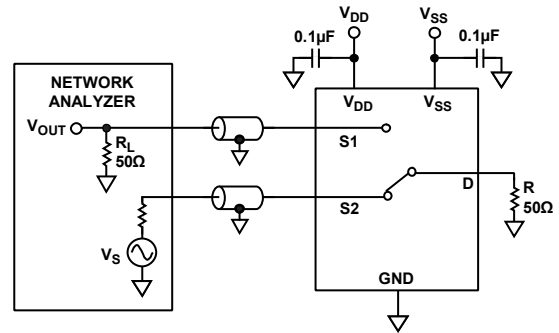


Figure 27. Channel-to-Channel Crosstalk

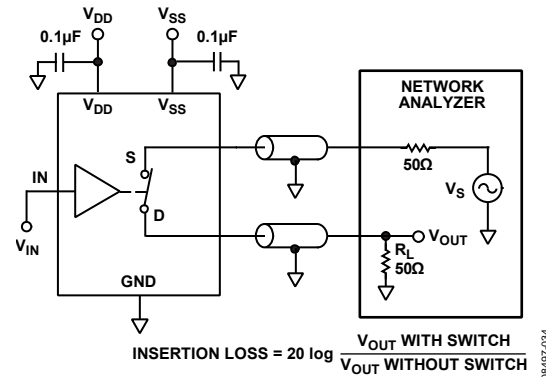


Figure 28. Insertion Loss

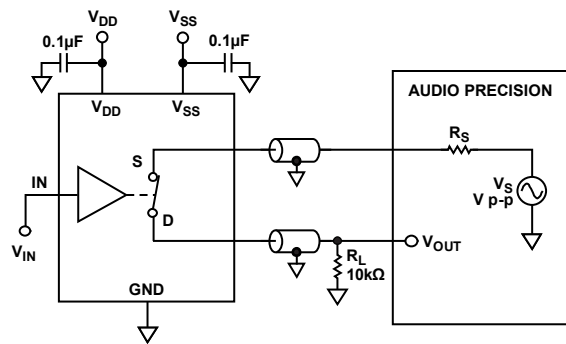


Figure 29. THD + Noise

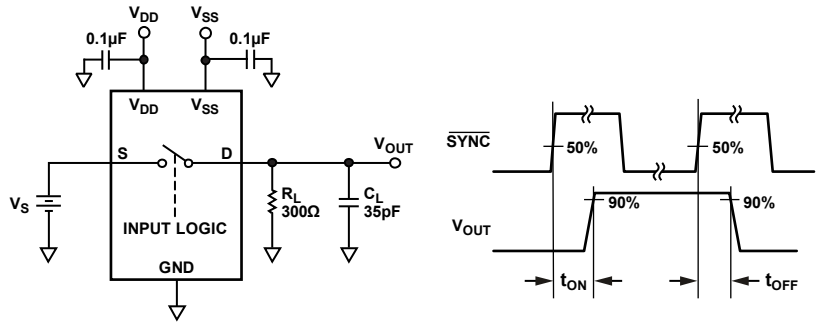


Figure 30. Switching Times

06497-029

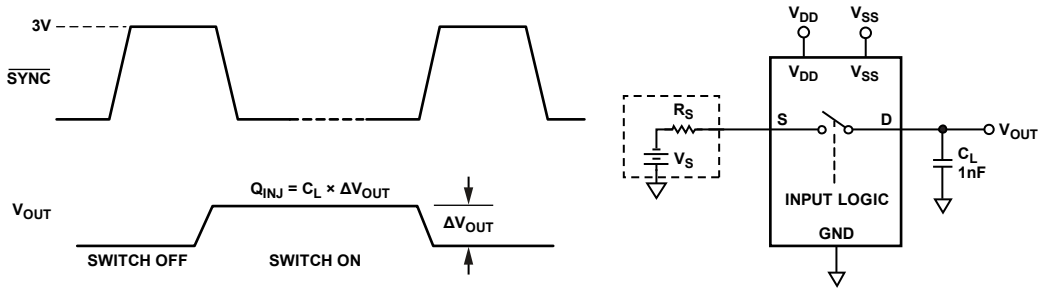


Figure 31. Charge Injection

06497-031

TERMINOLOGY

I_{DD}

The positive supply current.

I_{SS}

The negative supply current.

V_D (V_S)

The analog voltage on Terminal Dx or Terminal Sx.

R_{ON}

The ohmic resistance between Terminal Dx and Terminal Sx.

ΔR_{ON}

The difference between the R_{ON} of any two channels.

$R_{FLAT(ON)}$

Flatness is defined as the difference between the maximum and minimum value of on resistance, as measured over the specified analog signal range.

I_S (Off)

The source leakage current with the switch off.

I_D (Off)

The drain leakage current with the switch off.

I_D, I_S (On)

The channel leakage current with the switch on.

V_{INL}

The maximum input voltage for Logic 0.

V_{INH}

The minimum input voltage for Logic 1.

I_{INL} (I_{INH})

The input current of the digital input.

C_S (Off)

The off switch source capacitance, measured with reference to ground.

C_D (Off)

The off switch drain capacitance, measured with reference to ground.

C_D, C_S (On)

The on switch capacitance, measured with reference to ground.

C_{IN}

The digital input capacitance.

t_{ON}

The delay between applying the digital control input and the output switching on. See Figure 30.

t_{OFF}

The delay between applying the digital control input and the output switching off. See Figure 30.

Charge Injection

A measure of the glitch impulse transferred from the digital input to the analog output during switching.

Off Isolation

A measure of unwanted signal coupling through an off switch.

Crosstalk

A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.

Bandwidth

The frequency at which the output is attenuated by 3 dB.

On Response

The frequency response of the on switch.

Insertion Loss

The loss due to the on resistance of the switch.

THD + N

The ratio of the harmonic amplitude plus noise of the signal to the fundamental.

AC Power Supply Rejection Ratio (ACPSRR)

A measure of the ability of a device to avoid coupling noise and spurious signals that appear on the supply voltage pin to the output of the switch. The dc voltage on the device is modulated by a sine wave of 0.62 V p-p. The ratio of the amplitude of signal on the output to the amplitude of the modulation is the ACPSRR.

THEORY OF OPERATION

The ADG1414 is a set of serially controlled, octal SPST switches. Each of the eight bits of the 8-bit write corresponds to one switch of the device. A Logic 1 in the particular bit position turns the switch on, whereas a Logic 0 turns the switch off. Because an individual bit independently controls each switch, this independence provides the option of having any, all, or none of the switches turned on.

SERIAL INTERFACE

The ADG1414 has a 3-wire serial interface ($\overline{\text{SYNC}}$, SCLK, and DIN pins) that is compatible with SPI, QSPI, and MICROWIRE interface standards, as well as most DSPs. See Figure 2 for a timing diagram of a typical write sequence.

The write sequence begins by bringing the $\overline{\text{SYNC}}$ line low, which enables the input shift register. Data from the DIN line is clocked into the 8-bit input shift register on the falling edge of SCLK. The serial clock frequency can be as high as 50 MHz, making the ADG1414 compatible with high speed DSPs.

Data can be written to the shift register in more or less than eight bits. In each case, the shift register retains the last eight bits that were written. When all eight bits have been written into the shift register, the $\overline{\text{SYNC}}$ line is brought high again. The switches are updated with the new configuration, and the input shift register is disabled. With $\overline{\text{SYNC}}$ held high, the input shift register is disabled; therefore, further data or noise on the DIN line has no effect on the shift register.

Data appears on the SDO pin on the rising edge of SCLK suitable for daisy chaining or readback, delayed by eight bits.

INPUT SHIFT REGISTER

The input shift register is eight bits wide (see Table 10). Each bit controls one switch. These data bits are transferred to the switch register on the rising edge of $\overline{\text{SYNC}}$.

Table 10. ADG1414 Input Shift Register Bit Map¹

| MSB | | | | LSB | | | |
|-----|-----|-----|-----|-----|-----|-----|-----|
| DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 |
| S8 | S7 | S6 | S5 | S4 | S3 | S2 | S1 |

¹ Logic 0 = switch off, and Logic 1 = switch on.

POWER-ON RESET

The ADG1414 contains a power-on reset circuit. On power-up of the device, all switches are in the off condition and the internal shift register is filled with zeros and remains so until a valid write takes place.

The device also has a $\overline{\text{RESET}}/\text{V}_L$ pin. Under normal operation, drive the $\overline{\text{RESET}}/\text{V}_L$ pin with a 2.7 V to 5 V supply and pull the pin low for short period of time (15 ns is sufficient) to complete the hardware reset.

When using the $\overline{\text{RESET}}/\text{V}_L$ pin to do a hardware reset, drive all other SPI pins ($\overline{\text{SYNC}}$, SCLK, and DIN) low. This is to prevent current flow due to ESD protection diodes on the V_L pin to the SPI pins.

When the $\overline{\text{RESET}}/\text{V}_L$ pin is low, all switches are off and the appropriate registers are cleared to 0.

DAISY CHAINING

For systems that contain several switches, the SDO pin can be used to daisy-chain several devices together. The SDO pin can also be used for diagnostic purposes and provide serial readback, wherein the user can read back the switch contents.

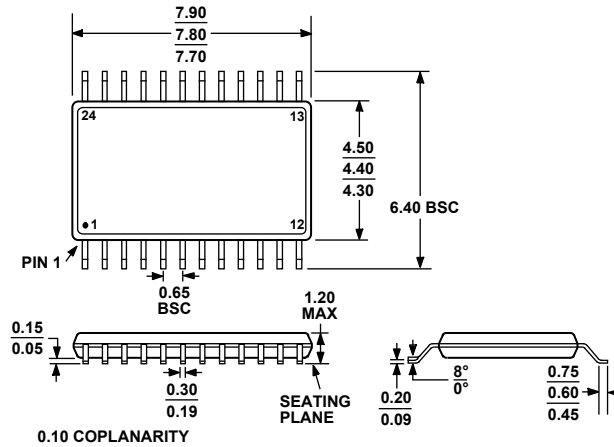
SDO is an open-drain output that must be pulled to the V_L supply with an external resistor.

The SCLK is continuously applied to the input shift register when $\overline{\text{SYNC}}$ is low. If more than eight clock pulses are applied, the data ripples out of the shift register and appears on the SDO line. This data is clocked out on the rising edge of SCLK and is valid on the falling edge. By connecting this line to the DIN input on the next device in the chain, a multiswitch interface is constructed. Each device in the system requires eight clock pulses; therefore, the total number of clock cycles must equal 8N, where N is the total number of devices in the chain.

When the serial transfer to all devices is complete, $\overline{\text{SYNC}}$ is taken high. This prevents any further data from being clocked into the input shift register.

The serial clock can be a continuous or a gated clock. A continuous SCLK source can be used only if $\overline{\text{SYNC}}$ can be held low for the correct number of clock cycles. In gated clock mode, a burst clock containing the exact number of clock cycles must be used, and $\overline{\text{SYNC}}$ must be taken high after the final clock to latch the data. Gated clock mode reduces power consumption by reducing the active clock time.

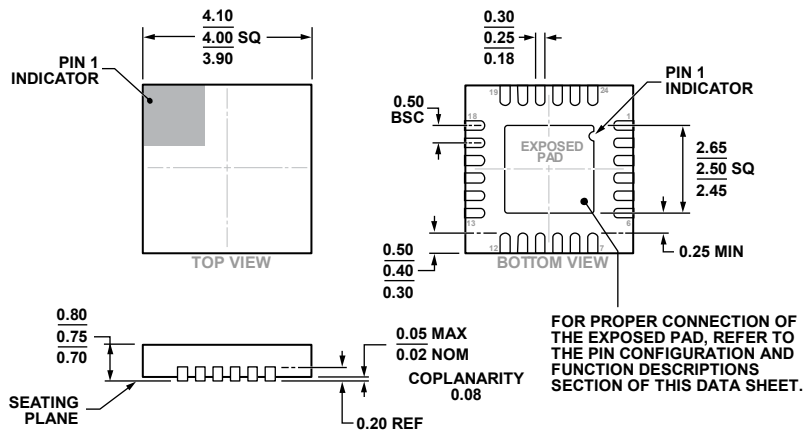
OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-153-AD

Figure 32. 24-Lead Thin Shrink Small Outline Package [TSSOP] (RU-24)

Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MO-220-WGGD.

Figure 33. 24-Lead Lead Frame Chip Scale Package [LFCSP] 4 mm × 4 mm Body and 0.75 mm Package Height (CP-24-7)

Dimensions shown in millimeters

08-11-2013-A

ORDERING GUIDE

| Model ¹ | Temperature Range | Package Description | Package Option |
|--------------------|-------------------|---|----------------|
| ADG1414BRUZ | -40°C to +125°C | 24-Lead Thin Shrink Small Outline Package [TSSOP] | RU-24 |
| ADG1414BRUZ-REEL7 | -40°C to +125°C | 24-Lead Thin Shrink Small Outline Package [TSSOP] | RU-24 |
| ADG1414BCPZ-REEL7 | -40°C to +125°C | 24-Lead Lead Frame Chip Scale Package [LFCSP] | CP-24-7 |

¹ Z = RoHS Compliant Part.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View ADG1414BCPZ-REEL7 on WIN SOURCE](#)
- ⊖ [Analog Devices Inc. Information](#)

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- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management